

MOUNTING BODY MANUFACTURING METHOD AND ANISOTROPIC CONDUCTIVE FILM

ABSTRACT

5

A method for manufacturing a mounting body comprising: a mounting step of mounting an electronic component onto a wiring board via an anisotropic conductive film containing a binder having an epoxy resin as a primary constituent and conductive particles having a compressive hardness (K) of 500 kgf / mm² or more when

10

compressively deformed by 10%, wherein a relation between a thickness (A) of the binder and an average particle diameter (B) is $0.6 \leq B / A \leq 1.5$ and an elastic modulus of the binder after curing is 50 MPa or more at 100°C; and a remounting step of mechanically peeling to detach the electronic component and the wiring board in the case of a problem occurring in mounting of the mounting step and reusing the wiring board to

15

[No Suitable Figure]